

For Immediate Release

Contact:

Greg Starrett

National Sales Manager

Greg@kokiamerica.com

When Cleaning Gets Hard, Collaboration Gets to Work: KOKI and ZESTRON to Host Technical Webinar on Solving Low-Standoff Challenges

Blue Ash, OH – May 4, 2026 – Have you ever had a process issue, called a supplier, and heard: “*Yeah, we don’t think it’s our product causing the issue*”?

KOKI Solder America and ZESTRON Corporation take a different approach, one rooted in shared responsibility, technical collaboration, and a commitment to solving the full process, not just isolated steps.

On Tuesday, May 12th at 10:00 AM PT / 12:00 PM CT / 1:00 PM ET, KOKI and ZESTRON will host a joint technical webinar titled:

“When Cleaning Gets Hard: Solving Low-Standoff Challenges with Advanced No-Clean Solder Pastes”

Presented by Shantanu Joshi (KOKI) and Jigar Patel (ZESTRON), the session will address one of the most persistent challenges in electronics manufacturing: achieving effective cleaning beneath low-standoff components without compromising reliability or process efficiency.

A Process-Level Problem Requires a Process-Level Solution

Low-standoff components create inherently difficult cleaning conditions, where flux residues become trapped beneath tight geometries. Traditional approaches often force trade-offs, more aggressive cleaning chemistries, slower belt speeds, or increased cycle times, all of which impact throughput and cost.

This webinar explores a different path.

By aligning solder paste formulation with cleaning process optimization, KOKI and ZESTRON demonstrate how engineered low-residue, no-clean solder pastes can significantly improve cleanability while maintaining print performance, wetting behavior, and long-term reliability.

Data-Driven Insights from Real-World Testing

Attendees will gain access to test data generated through controlled soldering and cleaning trials, including analysis of:

- Flux residue chemistry and its impact on under-component cleanliness
- Cleaning chemistry concentration and its relationship to removal efficiency

- Belt speed optimization and throughput implications
- Process window improvements that reduce the need for aggressive cleaning conditions

The results highlight how a coordinated approach between materials and process engineering can reduce overall manufacturing cost while maintaining stringent reliability standards.

More Than Materials—A Shared Engineering Mindset

“What makes this collaboration unique is the mindset,” said Shantanu Joshi of KOKI Solder America. “We don’t view challenges as belonging to one part of the process. If it affects the outcome, it’s our problem, and we work alongside partners like ZESTRON to solve it.”

ZESTRON brings deep expertise in precision cleaning analytics and chemistry, while KOKI contributes advanced solder paste development, including low-residue formulations engineered for complex assemblies. Together, the two companies provide a holistic view of how upstream material choices directly influence downstream cleaning performance.

Register today: <https://meet.zoho.com/myut-lxb-jwz>

About KOKI

Founded in 1964, KOKI is a global leader in advanced soldering materials, focused on innovation, sustainability, and regulatory compliance. In addition to its materials portfolio, KOKI offers in-depth technical services and analytical support to help customers optimize soldering performance across a wide range of applications worldwide.